

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ22DN20NS3 G	**Issued**	20. March 2021
MA#	MA000862680		
Package	PG-TSDSON-8-1	**Weight***	36.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.916	2.53	2.53	25307	25307
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		261	
	non noble metal	iron	7439-89-6	0.189	0.52		5230	
	non noble metal	copper	7440-50-8	7.689	21.24	21.80	212357	217913
wire	non noble metal	copper	7440-50-8	0.046	0.13	0.13	1257	1257
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1024	
	plastics	epoxy resin	-	1.909	5.27		52727	
	inorganic material	silicondioxide	60676-86-0	16.589	45.81	51.18	458159	511910
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10221	10221
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2231	2231
solder	non noble metal	tin	7440-31-5	0.024	0.07		657	
	noble metal	silver	7440-22-4	0.030	0.08		821	
	non noble metal	lead	7439-92-1	1.135	3.14	3.29	31358	32836
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			32	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2596	
	non noble metal	copper	7440-50-8	3.816	10.54	10.81	105391	108149
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2164	
	non noble metal	copper	7440-50-8	3.182	8.79	9.02	87877	90176
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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